

NOTES, UNLESS OTHERWISE SPECIFIED:

1. The netname "P12V_SUPPLY" represents connection to the +12V input power.
2. The netname "P6P2V" represents connection to the +6.2V power buss.
3. The netname "V5P0VADS" represents connection to the +5.0V power buss.
4. The netname "V3P3VADS" represents connection to the +3.3V power buss
5. The netname "V2P5VREF" represents connection to the +2.5V reference buss
6. The netname "V2P5VREFBUF" represents connection to the +2.5V buffered reference buss.
7. The netname "GND" represents connection to the ground plane.
8. A "Z" suffix on a signal name indicates an active low signal.
9. All components with designators "U*", "Q*", and "D*" are electrostatic discharge sensitive.
10. All resistor values are in ohms.
11. All capacitor values in microfarads unless otherwise specified.



COMPUTER GENERATED DRAWING - DO NOT REVISE MANUALLY

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
-	Draft Release	09/23/2013	HPC
A	ECO 2136062: REV A Release	11/09/2013	HPC
B	ECO 2138296: REV B Release	12/05/2013	GW
C	ECO 2139940: REV C Release	02/14/2014	HPC
D	ECO 2140577: REV D Release	03/12/2014	HPC

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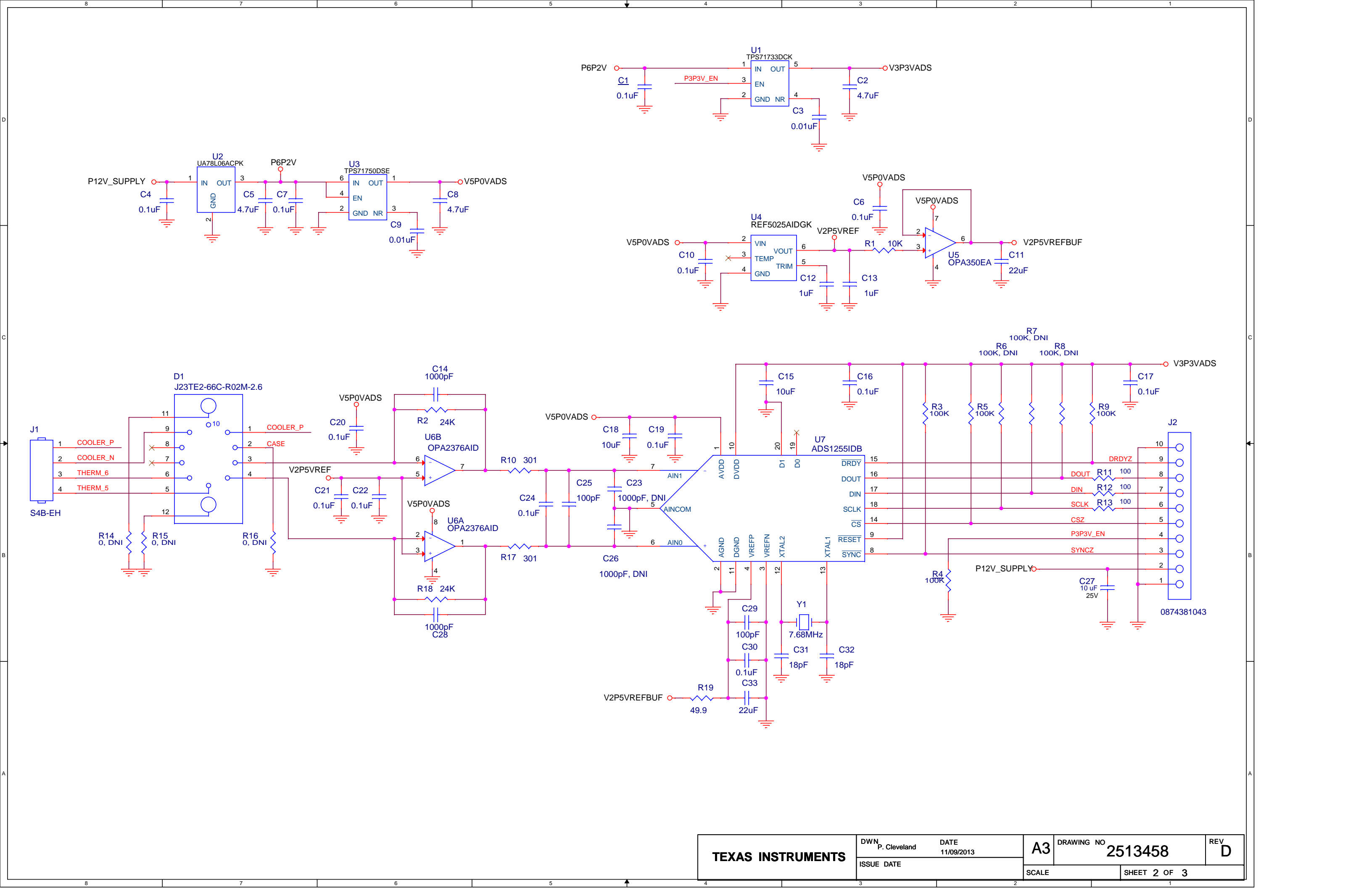
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		ENGR Eric Pruett				
		APVD Joe Siddall				
		MFG		TITLE ESD, NIRscan Detector, Amplifier, ADS		
	0314CP	QA				
NEXT ASSY	USED ON			A3	DRAWING NO 2513458	REV D
APPLICATION		SW Allegro Design Entry 16.6			SCALE SHEET 1 of 3	



Revision History

Rev. -: Draft Release ~ 09/23/2013
Rev. A: ECO 2136062 ~ 11/09/2013
Rev. B: ECO 2138296 ~ 12/05/2013 ~ Change J2 Part Number
Rev. C: ECO 2139940 ~ 02/14/2014 ~ Up-date title block, disclaimer
Rev. D: ECO 2140577 ~ 03/12/2014 ~ Cut U7-9, U1-3; Wire J2-4 to U1-3; Cut R4 at P3P3VADS, Ground R4; Add R6, R7, R14, R15, R16, C23, & C26 to DNI list

Schematic Revision History

TEXAS INSTRUMENTS	DWN P. Cleveland	DATE 11/09/2013	A3	DRAWING NO 2513458		REV D
	ISSUE DATE					
				SCALE		SHEET 3 OF 3